

(0,635 mm) .025"

**BTS, BSS SERIES**

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTS or www.samtec.com?BSS

Insulator Material:

Liquid Crystal Polymer

Terminal Material (BTS):

Phosphor Bronze

Contact Material (BSS):

Phosphor Bronze

Plating: Au or Sn over

50µ" (1,27 µm) Ni

Current Rating: 1.8 A per pin

(1 pin powered per row)

Operating Temp Range:

-55°C to +125°C

RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max

Board Stacking:

For applications requiring more than two connectors per board or 100 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
 - Other platings
 - Other positions
- Contact Samtec.

OTHER SOLUTIONS

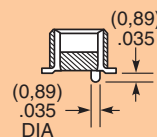
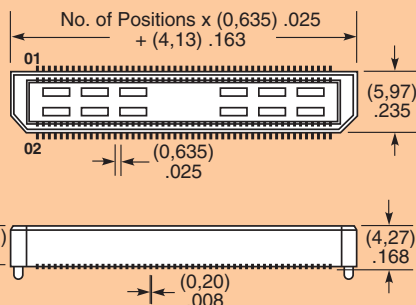
Edge Mount capability. Call for availability.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTS — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with:
BSS

-025, -050, -075, -100



-F
= Gold Flash on contact,
Matte Tin on tail

-L
= 10µ" (0,25 µm)
Gold on contact,
Matte Tin on tail

-K
= (7,00 mm) .275" DIA
Polyimide Film Pick
& Place Pad

-TR
= Tape & Reel
(~100 positions
maximum)

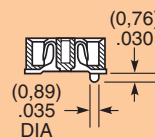
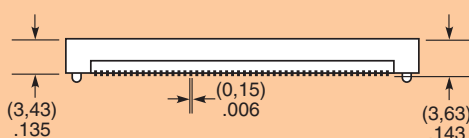
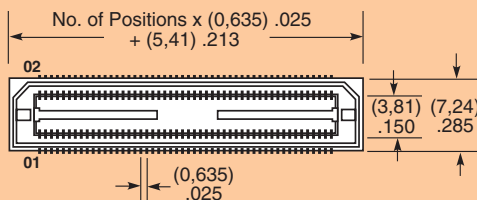


• Passes
10 year MFG

BSS — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with:
BTS

-025, -050, -075, -100



-F
= Gold Flash on contact,
Matte Tin on tail

-L
= 10µ" (0,25 µm)
Gold on contact,
Matte Tin on tail

-TR
= Tape & Reel
(~100 positions
maximum)

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM